

08-07-2006



103287204

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies):

Ken-ichi NONAKA (7/12/2006), Hideki  
HASHIMOTO (7/12/2006), Seiichi YOKOYAMA  
(7/12/2006), Hiroaki IWAKURO (7/12/2006),

Additional name(s) of conveying party(ies) attached? ☒ Yes ☐ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s): in parentheses after inventor name

☒ Assignment ☐ Merger ☐ Change of Name

☐ Security Agreement ☐ Joint Research Agreement

☐ Government Interest Assignment

☐ Executive Order 9424, Confirmatory License

☐ Other

2. Name and address of receiving party(ies)

Name: Honda Motor Co., Ltd.

Internal Address: \_\_\_\_\_

Street Address: \_\_\_\_\_

1-1, Minami-Aoyama 2-chome, Minato-ku

City: Tokyo

State: \_\_\_\_\_

Country: JAPAN Zip: \_\_\_\_\_

Additional name(s) & address(es) attached: ☒ Yes ☐ No

4. Application or patent number(s):

☒ This document is being filed together with a new application.

A. Patent Application No.(s)

NEW

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: James M. Slattery  
BIRCH, STEWART, KOLASCH & BIRCH,  
LLP

Internal Address: Atty. Dkt.: 0943-0169PUS1

Street Address: 8110 Gatehouse Road  
Suite 100 East  
P.O. Box 747

City: Falls Church

State: VA Zip: 22040-0747

Phone Number: (703) 205-8000

Fax Number: (703) 205-8050

Email Address: mailroom@bskb.com

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

☐ Authorized to be charged by credit card

☐ Authorized to be charged to deposit account

☒ Enclosed

☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers \_\_\_\_\_

Expiration Date \_\_\_\_\_

b. Deposit Account Number \_\_\_\_\_

Authorized User Name \_\_\_\_\_

9. Signature:

James M. Slattery leg pb  
32,334  
Signature

August 1, 2006

Date

James M. Slattery - 28,380

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

6

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11/496627



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08/02/2006 HLE333 00000085 11496627

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RECORDATION FORM COVER SHEET  
(continued)

## Additional Conveying Party(ies)/Execution Date(s) (1. Continued):

Koichi NISHIKAWA (7/12/2006), Masaaki SHIMIZU (7/12/2006), and Yusuke FUKUDA (7/12/2006)

## Additional Assignees (2. Continued):

Assignee Name: Shindengen Electric Manufacturing Co., Ltd.

Internal Address:

Street Address:

2-1, Ohtemachi 2-chome, Chiyoda-ku

City: Tokyo State: \_\_\_\_\_ Country: Japan Zip: \_\_\_\_\_

Assignee Name: \_\_\_\_\_

Internal Address:

Street Address:

City: \_\_\_\_\_ State: \_\_\_\_\_ Country: \_\_\_\_\_ Zip: \_\_\_\_\_

Assignee Name: \_\_\_\_\_

Internal Address:

Street Address:

City: \_\_\_\_\_ State: \_\_\_\_\_ Country: \_\_\_\_\_ Zip: \_\_\_\_\_

## Additional Applications and/or Patents (4. Continued):

Additional Patent Application Numbers

4A. Continued:

Additional Patent Numbers

4B. Continued:

Additional numbers attached?

☐

Yes

☐

No

**BIRCH, STEWART, KOLASCH & BIRCH, LLP**UNITED STATES PATENT RIGHTS, OR  
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS**ASSIGNMENT**Application No. NEWFiled 8/1/06Insert Name(s)  
of Inventor(s)

\*\*\* (Given Name FAMILY NAME (ALL CAPS)) \*\*\*

WHEREAS,	Ken-ichi NONAKA	;	Hideki HASHIMOTO
Seiichi YOKOYAMA	Hiroaki IWAKURO	;	Koichi NISHIKAWA
Masaaki SHIMIZU	Yusuke FUKUDA	;	
		;	
		;	
		;	

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in  
ION IMPLANTATION MASK AND METHOD FOR MANUFACTURING SAME, SILICON CARBIDE  
Insert Title SEMICONDUCTOR DEVICE USING ION IMPLANTATION MASK, AND METHOD FOR  
of Invention MANUFACTURING SAME

for which an application for Letters Patent of the United States of America has been executed by the undersigned (except in the case of a provisional application).

Insert Date  
of Signing of  
Applicationon July 12, 2006; andInsert Name  
of Assignee

(A): Honda Motor Co., Ltd.  
WHEREAS, (B): Shindengen Electric Manufacturing Co., Ltd.

Insert Address  
of Assignee

(A): 1-1, Minami-Aoyama 2-chome, Minato-ku, Tokyo, Japan  
of (B): 2-1, Ohtemachi 2-chome, Chiyoda-ku, Tokyo, Japan

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and

CHECK BOX  
IF APPROPRIATE☐ in any foreign countries.

NOW, THEREFORE, in consideration of the sum of Ten Dollars (\$10.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents does sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries;

and to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.

Attorney Docket No. \_\_\_\_\_

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree (s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Birch, Stewart, Kolasch & Birch, LLP the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date <u>July 12, 2006</u>	Name of Inventor <u>Ken-ichi NONAKA</u> (signature) <u>Kenichi Nonaka</u>
Date <u>July 12, 2006</u>	Name of Inventor <u>Hideki HASHIMOTO</u> (signature) <u>Hideki Hashimoto</u>
Date <u>July 12, 2006</u>	Name of Inventor <u>Seiichi YOKOYAMA</u> (signature) <u>Seiichi Yokoyama</u>
Date _____	Name of Inventor <u>Hiroaki IWAKURO</u> (signature) _____
Date _____	Name of Inventor <u>Koichi NISHIKAWA</u> (signature) _____
Date _____	Name of Inventor <u>Masaaki SHIMIZU</u> (signature) _____

Attorney Docket No. \_\_\_\_\_

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree (s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

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In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date \_\_\_\_\_

Name of Inventor Ken-ichi NONAKA  
(signature)

Date \_\_\_\_\_

Name of Inventor Hideki HASHIMOTO  
(signature)

Date \_\_\_\_\_

Name of Inventor Seiichi YOKOYAMA  
(signature)Date July 12, 2006Name of Inventor Hiroaki IWAKURO  
(signature)Date July 12, 2006Name of Inventor Koichi NISHIKAWA  
(signature)Date July 12, 2006Name of Inventor Masaaki SHIMIZU  
(signature)

Attorney Docket No. \_\_\_\_\_

Date July 12, 2006,

Name of Inventor Yusuke FUKUDA  
(signature)

*Yusuke Fukuda*

Date \_\_\_\_\_,

Name of Inventor \_\_\_\_\_  
(signature)

Date \_\_\_\_\_,

Name of Inventor \_\_\_\_\_  
(signature)

Date \_\_\_\_\_,

Name of Inventor \_\_\_\_\_  
(signature)

Date \_\_\_\_\_,

Name of Inventor \_\_\_\_\_  
(signature)

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Name of Inventor \_\_\_\_\_  
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Name of Inventor \_\_\_\_\_  
(signature)

Date \_\_\_\_\_,

Name of Inventor \_\_\_\_\_  
(signature)

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